

### **General Description**

The MAX9124 guad low-voltage differential signaling (LVDS) line driver is ideal for applications requiring high data rates, low power, and low noise. The MAX9124 is guaranteed to transmit data at speeds up to 800Mbps (400MHz) over controlled impedance media of approximately  $100\Omega$ . The transmission media may be printed circuit (PC) board traces, backplanes, or cables.

The MAX9124 accepts four LVTTL/LVCMOS input levels and translates them to LVDS output signals. Moreover, the MAX9124 is capable of setting all four outputs to a high-impedance state through two enable inputs, EN and EN, thus dropping the device to an ultra-low-power state of 16mW (typ) during high impedance. The enables are common to all four transmitters. Outputs conform to the ANSI TIA/EIA-644 LVDS standard.

The MAX9124 operates from a single +3.3V supply and is specified for operation from -40°C to +85°C. It is available in 16-pin TSSOP and SO packages. Refer to the MAX9125/ MAX9126 data sheet for guad LVDS line receivers.

#### **Features**

- ♦ Pin Compatible with DS90LV031A
- ♦ Guaranteed 800Mbps Data Rate
- ♦ 250ps Maximum Pulse Skew
- ♦ Conforms to TIA/EIA-644 LVDS Standard
- ♦ Single +3.3V Supply
- ♦ 16-Pin TSSOP and SO Packages

### **Ordering Information**

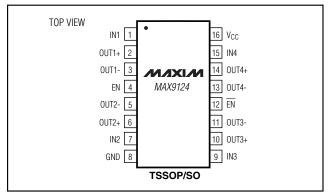
PART	TEMP. RANGE	PIN-PACKAGE
MAX9124EUE	-40°C to +85°C	16 TSSOP
MAX9124ESE	-40°C to +85°C	16 SO

### **Applications**

**Digital Copiers DSLAMs** Laser Printers Network Switches/Routers Cell Phone Base Stations Backplane Interconnect Add/Drop Muxes Clock Distribution

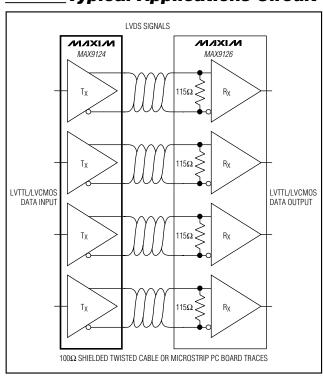
Digital Cross-Connects

## **Pin Configuration**



<sup>\*</sup> Future product—contact factory for availability.

## **Typical Applications Circuit**



#### **ABSOLUTE MAXIMUM RATINGS**

V <sub>CC</sub> to GND	0.3V to +4.0V
IN_, EN, EN to GND	0.3V to $(V_{CC} + 0.3V)$
OUT_+, OUT to GND	
Short-Circuit Duration (OUT_+, OUT)	
Continuous Power Dissipation ( $T_A = +70$ °C)	
16-Pin TSSOP (derate 9.4mW/°C above +	
16-Pin SO (derate 8.7mW/°C above +70°	C)696mW

Storage Temperature Range	65°C to +150°C
Maximum Junction Temperature	+150°C
Operating Temperature Range	40°C to +85°C
Lead Temperature (soldering, 10s)	+300°C
ESD Protection	
Human Body Model, OUT_+, OUT	±6kV

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

#### DC ELECTRICAL CHARACTERISTICS

 $(V_{CC} = +3.0 \text{V to } +3.6 \text{V}, R_L = 100\Omega \pm 1\%, T_A = -40 ^{\circ}\text{C}$  to  $+85 ^{\circ}\text{C}$ . Typical values are at  $V_{CC} = +3.3 \text{V}, T_A = +25 ^{\circ}\text{C}$ , unless otherwise noted.) (Notes 1, 2)

PARAMETER	SYMBOL CONDITIONS		MIN	TYP	MAX	UNITS
LVDS OUTPUT (OUT_+, OUT)						
Differential Output Voltage	V <sub>OD</sub>	Figure 1	250	368	450	mV
Change in Magnitude of V <sub>OD</sub> Between Complementary Output States	ΔV <sub>OD</sub>	Figure 1		1	25	mV
Offset Voltage	Vos	Figure 1	1.125	1.25	1.375	V
Change in Magnitude of Vos Between Complementary Output States	ΔVOS	Figure 1		4	25	mV
Output High Voltage	VoH				1.6	V
Output Low Voltage	V <sub>OL</sub>		0.90			V
Differential Output Short-Circuit Current (Note 3)	Iosp	Enabled, V <sub>OD</sub> = 0			-9	mA
Output Short-Circuit Current	los	OUT_+ = 0 at IN_ = V <sub>CC</sub> or OUT = 0 at IN_ = 0, enabled -3.8		-3.8	-9	mA
Output High-Impedance Current	loz	EN = low and $\overline{\text{EN}}$ = high, OUT_+ = 0 or V <sub>CC</sub> , OUT = 0 or V <sub>CC</sub> , R <sub>L</sub> = $\infty$	-10		10	μΑ
Power-Off Output Current	loff	$V_{CC}$ = 0 or open, OUT_+ = 0 or 3.6V, OUT = 0 or 3.6V, R <sub>L</sub> = $\infty$	-10		10	μA
INPUTS (IN_, EN, EN)			•			
High-Level Input Voltage	VIH		2.0		Vcc	V
Low-Level Input Voltage	V <sub>IL</sub>		GND		0.8	V
Input Current	I <sub>IN</sub>	IN_, EN, $\overline{\text{EN}} = 0$ or $V_{CC}$	-20		20	μΑ
SUPPLY CURRENT						
No-Load Supply Current	Icc	$R_L = \infty$ , $IN_{-} = V_{CC}$ or 0 for all channels		9.2	11	mA
Loaded Supply Current	ICCL	$R_L = 100\Omega$ , $IN = V_{CC}$ or 0 for all channels		22.7	30	mA
Disabled Supply Current	Iccz	Disabled, IN_ = $V_{CC}$ or 0 for all channels, EN = 0, $\overline{EN}$ = $V_{CC}$		4.9	6	mA

#### **SWITCHING CHARACTERISTICS**

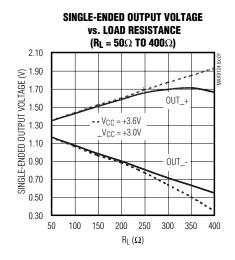
 $(V_{CC} = +3.0 \text{V to } +3.6 \text{V}, R_L = 100\Omega \pm 1\%, C_L = 10 \text{pF}, T_A = -40 ^{\circ}\text{C} \text{ to } +85 ^{\circ}\text{C}.$  Typical values are at  $V_{CC} = +3.3 \text{V}, T_A = +25 ^{\circ}\text{C}, \text{ unless otherwise noted.}) (Notes 4, 5, 6)$ 

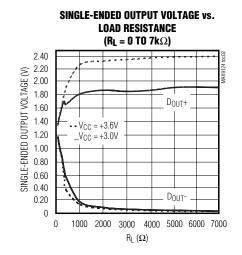
PARAMETER	PARAMETER SYMBOL CONDITIONS		MIN	TYP	MAX	UNITS
Differential Propagation Delay High to Low	t <sub>PHLD</sub>	Figures 2 and 3		1.42	2.0	ns
Differential Propagation Delay Low to High	tPLHD	Figures 2 and 3		1.44	2.0	ns
Differential Pulse Skew (Note 7)	tskD1	Figures 2 and 3		0.02	0.25	ns
Differential Channel-to-Channel Skew (Note 8)	tskD2	Figures 2 and 3			0.35	ns
Differential Part-to-Part Skew (Note 9)	tskD3	Figures 2 and 3			0.8	ns
Differential Part-to-Part Skew (Note 10)	tSKD4	Figures 2 and 3			1.2	ns
Rise Time	tTLH	Figures 2 and 3	0.1	0.35	0.7	ns
Fall Time	tTHL	Figures 2 and 3	0.1	0.35	0.7	ns
Disable Time High to Z	tpHZ	Figures 4 and 5			5	ns
Disable Time Low to Z	tplz	Figures 4 and 5			5	ns
Enable Time Z to High	tpzh	Figures 4 and 5			5	ns
Enable Time Z to Low	tpzL	Figures 4 and 5			5	ns
Maximum Operating Frequency (Note 11)	f <sub>MAX</sub>		400			MHz

- Note 1: Maximum and minimum limits over temperature are guaranteed by design and characterization. Devices are 100% tested at T<sub>A</sub> = +25°C.
- Note 2: Currents into the device are positive, and current out of the device is negative. All voltages are referenced to ground except Vop.
- Note 3: Guaranteed by correlation data.
- Note 4: AC parameters are guaranteed by design and characterization.
- Note 5: C<sub>L</sub> includes probe and jig capacitance.
- **Note 6:** Signal generator conditions for dynamic tests:  $V_{OL} = 0$ ,  $V_{OH} = 3V$ , f = 100MHz, 50% duty cycle,  $R_O = 50\Omega$ ,  $t_R \le 1$ ns,  $t_F \le 1$ ns (0% to 100%).
- Note 7: t<sub>SKD1</sub> is the magnitude difference of differential propagation delay. t<sub>SKD1</sub> = lt<sub>PHLD</sub> t<sub>PLHD</sub>l.
- Note 8: t<sub>SKD2</sub> is the magnitude difference of t<sub>PHLD</sub> or t<sub>PLHD</sub> of one channel to the t<sub>PHLD</sub> or t<sub>PLHD</sub> of another channel on the same device.
- Note 9: t<sub>SKD3</sub> is the magnitude difference of any differential propagation delays between devices at the same V<sub>CC</sub> and within 5°C of each other.
- Note 10: t<sub>SKD4</sub> is the magnitude difference of any differential propagation delays between devices operating over the rated supply and temperature ranges.
- **Note 11:**  $f_{MAX}$  signal generator conditions:  $V_{OL} = 0$ ,  $V_{OH} = 3V$ , f = 400MHz, 50% duty cycle,  $R_O = 50\Omega$ ,  $t_R \le 1$ ns,  $t_F \le 1$ ns (0% to 100%). Transmitter output criteria: duty cycle = 45% to 55%,  $V_{OD} \ge 250$ mV.

### Typical Operating Characteristics

 $(T_A = +25^{\circ}C)$ 





### **Pin Description**

PIN	NAME	FUNCTION
1, 7, 9, 15	IN_	LVTTL/LVCMOS Driver Inputs
2, 6, 10, 14	OUT_+	Noninverting LVDS Driver Outputs
3, 5, 11, 13	OUT	Inverting LVDS Driver Outputs
4, 12 EN, $\overline{\text{EN}}$ Driver Enable Inputs. The driver is disabled and in high impedance when EN is low and For other combinations of EN and $\overline{\text{EN}}$ , the outputs are active.		Driver Enable Inputs. The driver is disabled and in high impedance when EN is low and $\overline{\text{EN}}$ is high. For other combinations of EN and $\overline{\text{EN}}$ , the outputs are active.
8	GND	Ground
16	Vcc	Power-Supply Input. Bypass V <sub>CC</sub> to GND with 0.1µF and 0.001µF ceramic capacitors.

#### **Detailed Description**

The LVDS interface standard is a signaling method intended for point-to-point communication over a controlled-impedance medium as defined by the ANSI/TIA/EIA-644 and IEEE 1596.3 standards. The LVDS standard uses a lower voltage swing than other common communication standards, achieving higher data rates with reduced power consumption while reducing EMI emissions and system susceptibility to noise.

The MAX9124 is an 800Mbps quad differential LVDS driver that is designed for high-speed, point-to-point, and low-power applications. This device accepts LVTTL/LVCMOS input levels and translates them to LVDS output signals.

The MAX9124 generates a 2.5mA to 4.0mA output current using a current-steering configuration. This current-steering approach induces less ground bounce and no shoot-through current, enhancing noise margin and system speed performance. The driver outputs are short-circuit current limited and enter a high-impedance state when the device is not powered or is disabled.

The current-steering architecture of the MAX9124 requires a resistive load to terminate the signal and complete the transmission loop. Because the device switches current and not voltage, the actual output voltage swing is determined by the value of the termination resistor at the input of an LVDS receiver. Logic states are determined by the direction of current flow through the termination resistor. With a typical 3.7mA output current, the MAX9124 produces an output voltage of 370mV when driving a  $100\Omega$  load.

#### **Termination**

Because the MAX9124 is a current-steering device, no output voltage will be generated without a termination resistor. The termination resistors should match the differential impedance of the transmission line. Output voltage levels depend upon the value of the termination resistor. The MAX9124 is optimized for point-to-point interface with  $100\Omega$  termination resistors at the receiver inputs. Termination resistance values may range between  $90\Omega$  and  $132\Omega$ , depending on the characteristic impedance of the transmission medium.

### Applications Information

#### **Power-Supply Bypassing**

Bypass V<sub>CC</sub> with high-frequency, surface-mount ceramic  $0.1\mu F$  and  $0.001\mu F$  capacitors in parallel as

**Table 1. Input/Output Function Table** 

ENABLES		INPUTS	OUTPUTS		
EN	EN	IN_	OUT_+	OUT	
L	Н	Χ	Z	Z	
All other combinations		L	L	Н	
of ENAB	LE inputs	Н	Н	L	

close to the device as possible, with the smaller valued capacitor closest to  $\ensuremath{\text{VCC}}.$ 

#### **Differential Traces**

Output trace characteristics affect the performance of the MAX9124. Use controlled-impedance traces to match trace impedance to the transmission medium. Eliminate reflections and ensure that noise couples as common mode by running the differential trace pairs close together. Reduce skew by matching the electrical length of the traces. Excessive skew can result in a degradation of magnetic field cancellation.

Maintain the distance between the differential traces to avoid discontinuities in differential impedance. Avoid 90° turns and minimize the number of vias to further prevent impedance discontinuities.

#### **Cables and Connectors**

Transmission media should have a nominal differential impedance of  $100\Omega$ . To minimize impedance discontinuities, use cables and connectors that have matched differential impedance.

Avoid the use of unbalanced cables such as ribbon or simple coaxial cable. Balanced cables, such as twisted pair, offer superior signal quality and tend to generate less EMI due to canceling effects. Balanced cables tend to pick up noise as common mode, which is rejected by the LVDS receiver.

#### **Board Layout**

For LVDS applications, a four-layer PC board that provides separate power, ground, LVDS signals, and input signals is recommended. Isolate the LVTTL/LVCMOS and LVDS signals from each other to prevent coupling.

#### **Chip Information**

**TRANSISTOR COUNT: 2007** 

PROCESS: CMOS

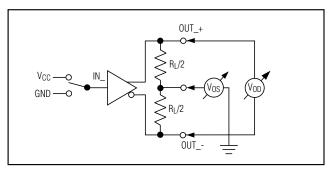


Figure 1. Driver VoD and Vos Test Circuit

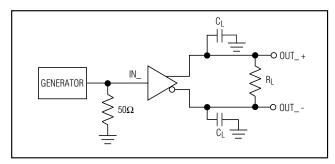


Figure 2. Driver Propagation Delay and Transition Time Test Circuit

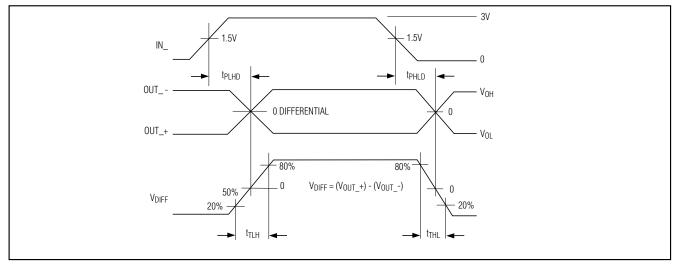


Figure 3. Driver Propagation Delay and Transition Time Waveforms

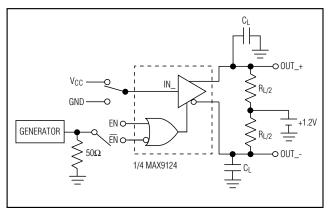


Figure 4. Driver High-Impedance Delay Test Circuit

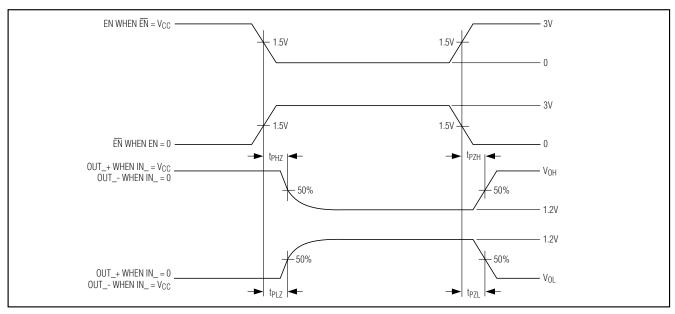
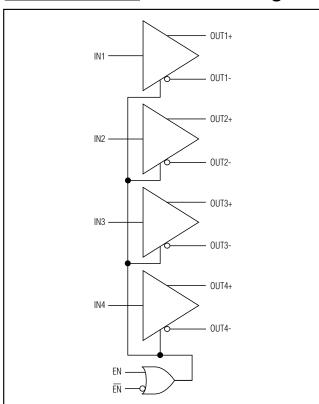
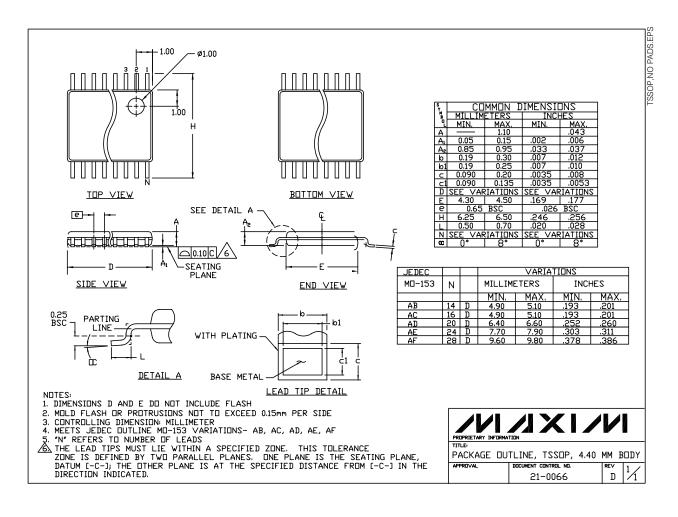


Figure 5. Driver High-Impedance Delay Waveform

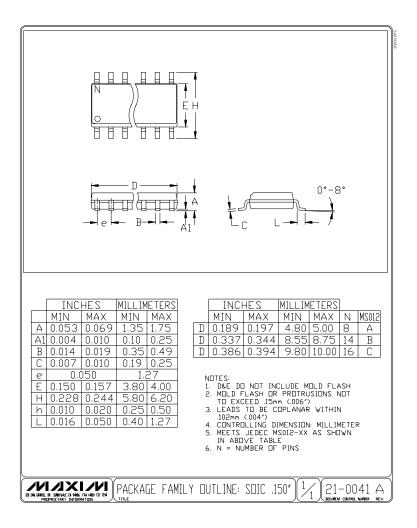
### **Functional Diagram**



### Package Information



### **Package Information (continued)**



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